



Materials Declaration

Package	LFCSP
Body Size	2 x 3
LeadCount	8
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	5.45 E-04	44307
SiO2 Filler	84	4.58 E-03	372181
Phenol Resin	5.5	3.00 E-04	24369
Carbon Black	0.5	2.72 E-05	2215

Molding Compound

Item	PPM	Method
Pb	4.40	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPaes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	5.86 E-03	476967
Fe	2.35	1.41 E-04	11496
P	0.03	1.80 E-06	147
Zn	0.12	7.22 E-06	587

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.33 E-04	10854

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	5.27 E-05	4286

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.33 E-04	10847

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	4.40 E-04	35822

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	22	1.60 E-05	1303
Ag Filler	78	5.68 E-05	4619

Package Totals

Weight (g)	PPM
1.23 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



Materials Declaration

Package	LFCSP
Body Size	2 x 3
LeadCount	8
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	5.45 E-04	44336
SiO2 Filler	84	4.58 E-03	372420
Phenol Resin	5.5	3.00 E-04	24385
Carbon Black	0.5	2.72 E-05	2217

Molding Compound

Item	PPM	Method
Pb	4.40	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICPaes)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	5.86 E-03	477274
Fe	2.35	1.41 E-04	11504
P	0.03	1.80 E-06	147
Zn	0.12	7.22 E-06	587

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.33 E-04	10861

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.48 E-05	3646
Pb	15	7.90 E-06	643

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.33 E-04	10854

Chip

	% of Chip	Weight (g)	PPM
Si	100	4.40 E-04	35845

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	22	1.60 E-05	1304
Ag Filler	78	5.68 E-05	4622

Package Totals

	Weight (g)	PPM
	1.23 E-02	1000000

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